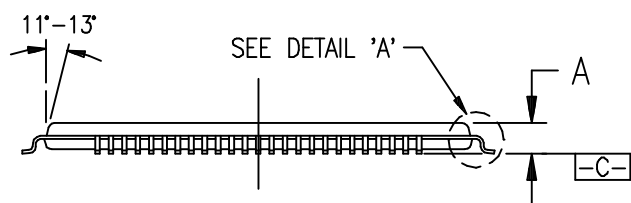
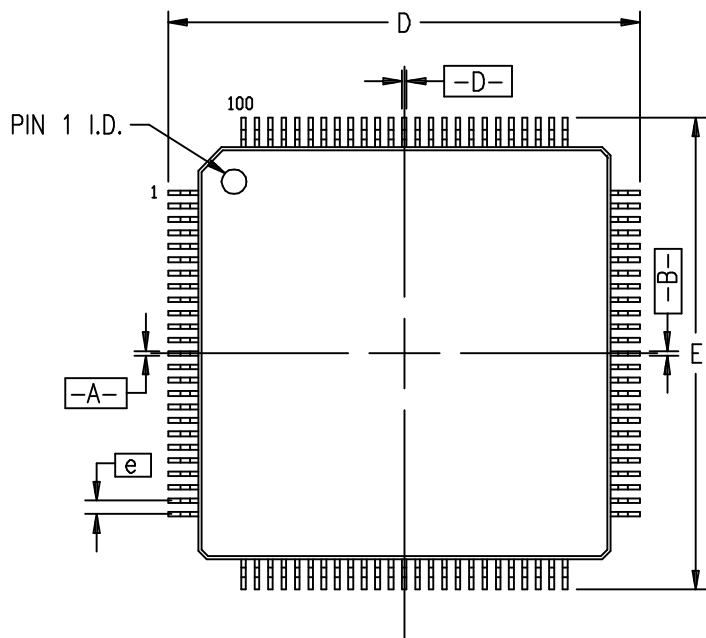
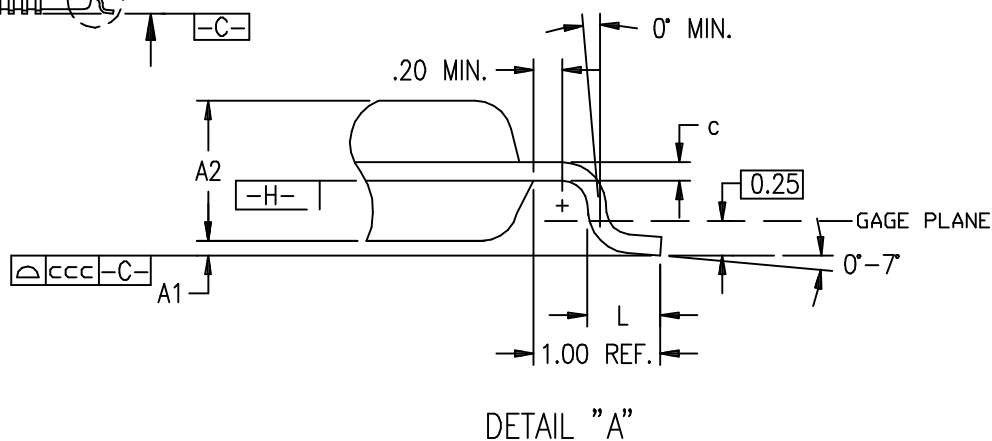
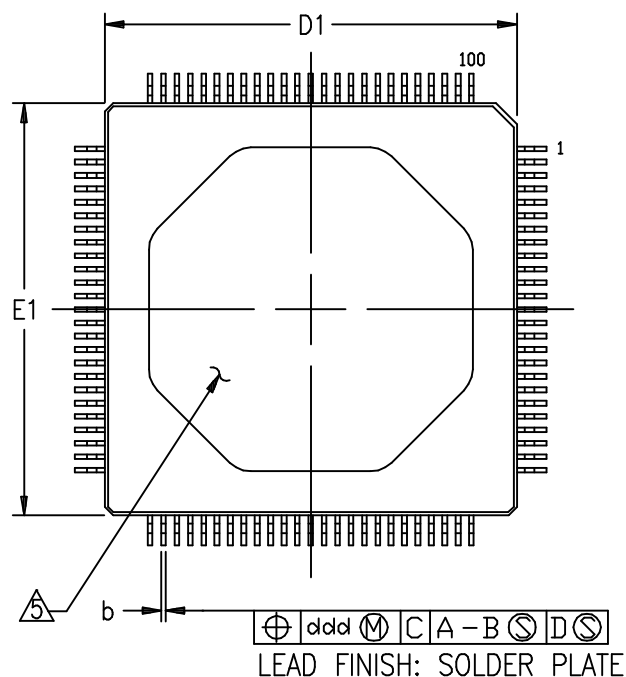


TOP VIEW



BOTTOM VIEW



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.10	1.25	1.60
A <sub>1</sub>	0.05	0.10	0.15
A <sub>2</sub>	1.35	1.40	1.45
D/E	16.00 BSC		
D <sub>1</sub> /E <sub>1</sub>	14.00 BSC		
L	0.45	0.60	0.75
e	0.50 BSC		
b	0.17	0.22	0.27
c	0.09	0.10	0.20
ccc	0.08	0.10	0.15
ddd	0.08	0.10	0.15

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982
2. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.
3. PACKAGE TOP DIMENSION MAY BE SMALLER THAN THE BOTTOM DIMENSION BY 0.15mm.
4. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-026-BED
5. THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS "HT".

100-PIN TQFP (TQ100)  
100-PIN HEAT SINK TQFP (HT100)